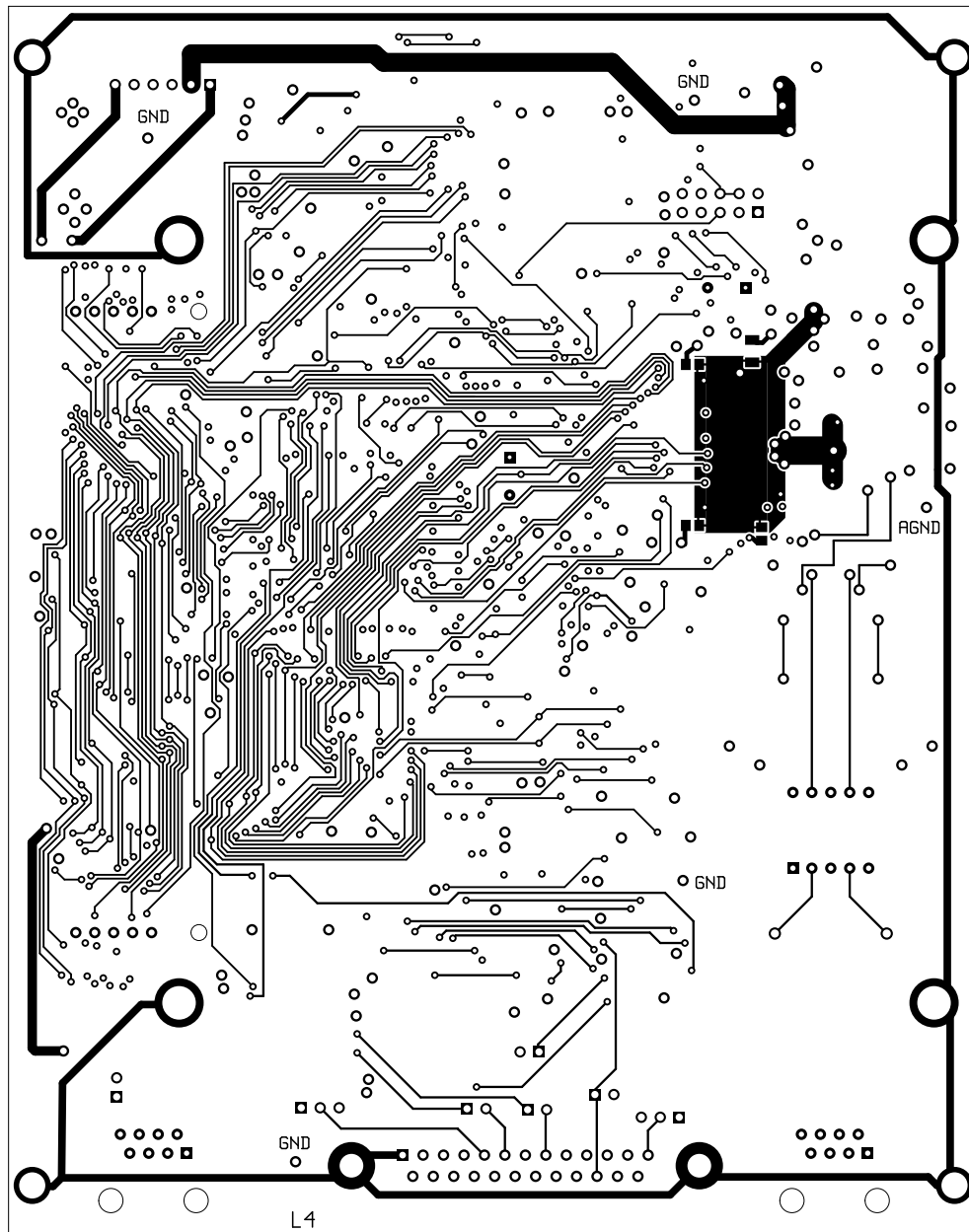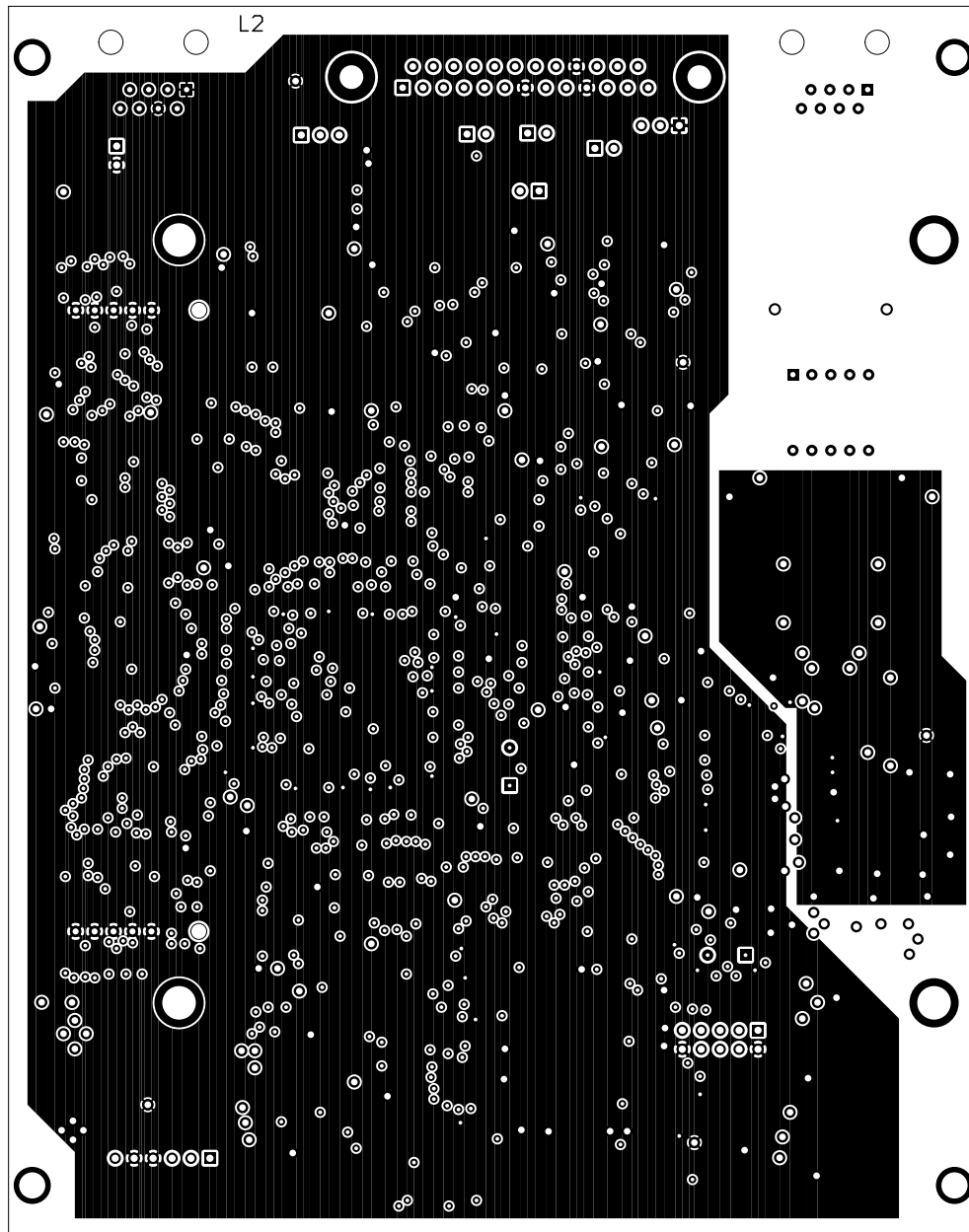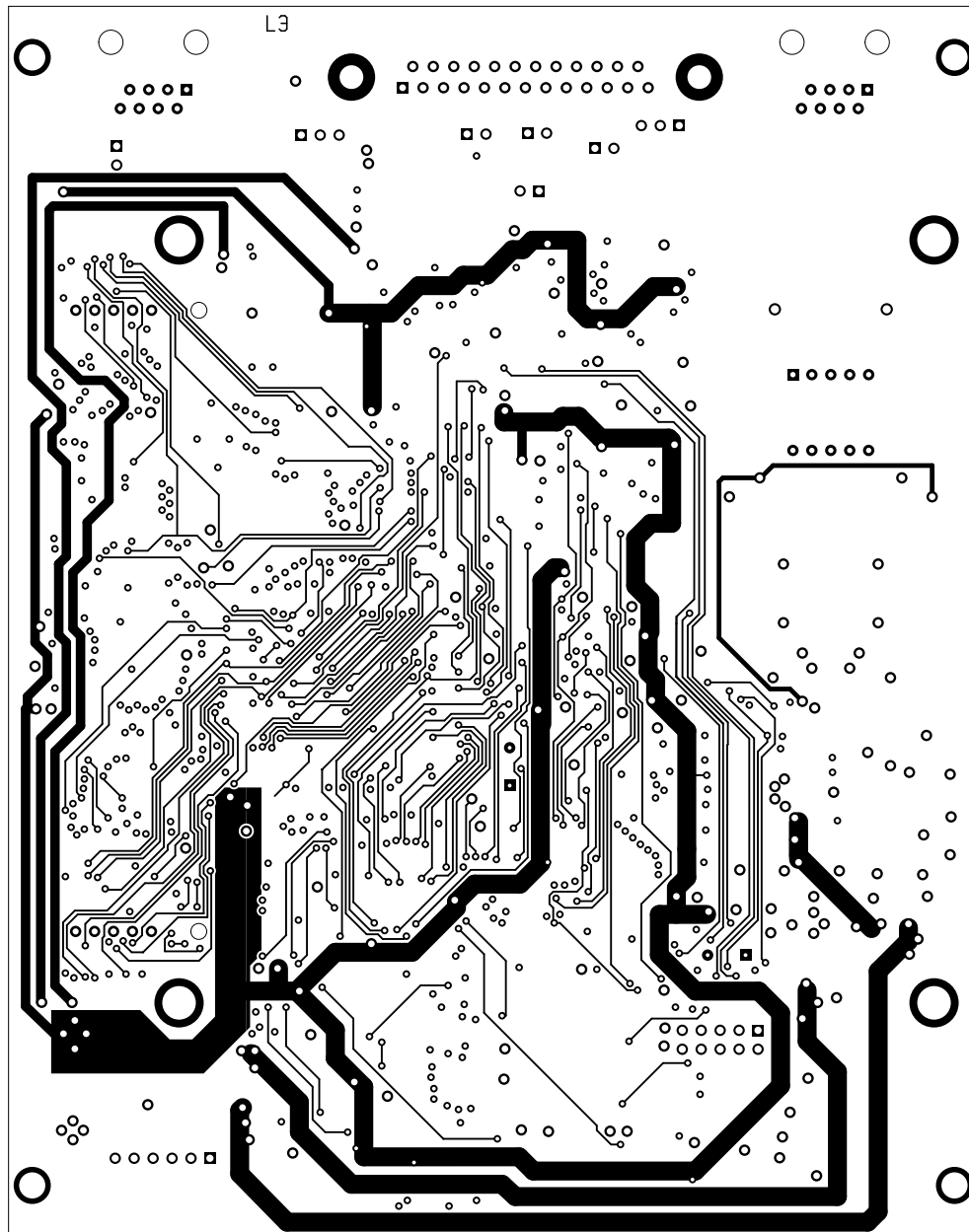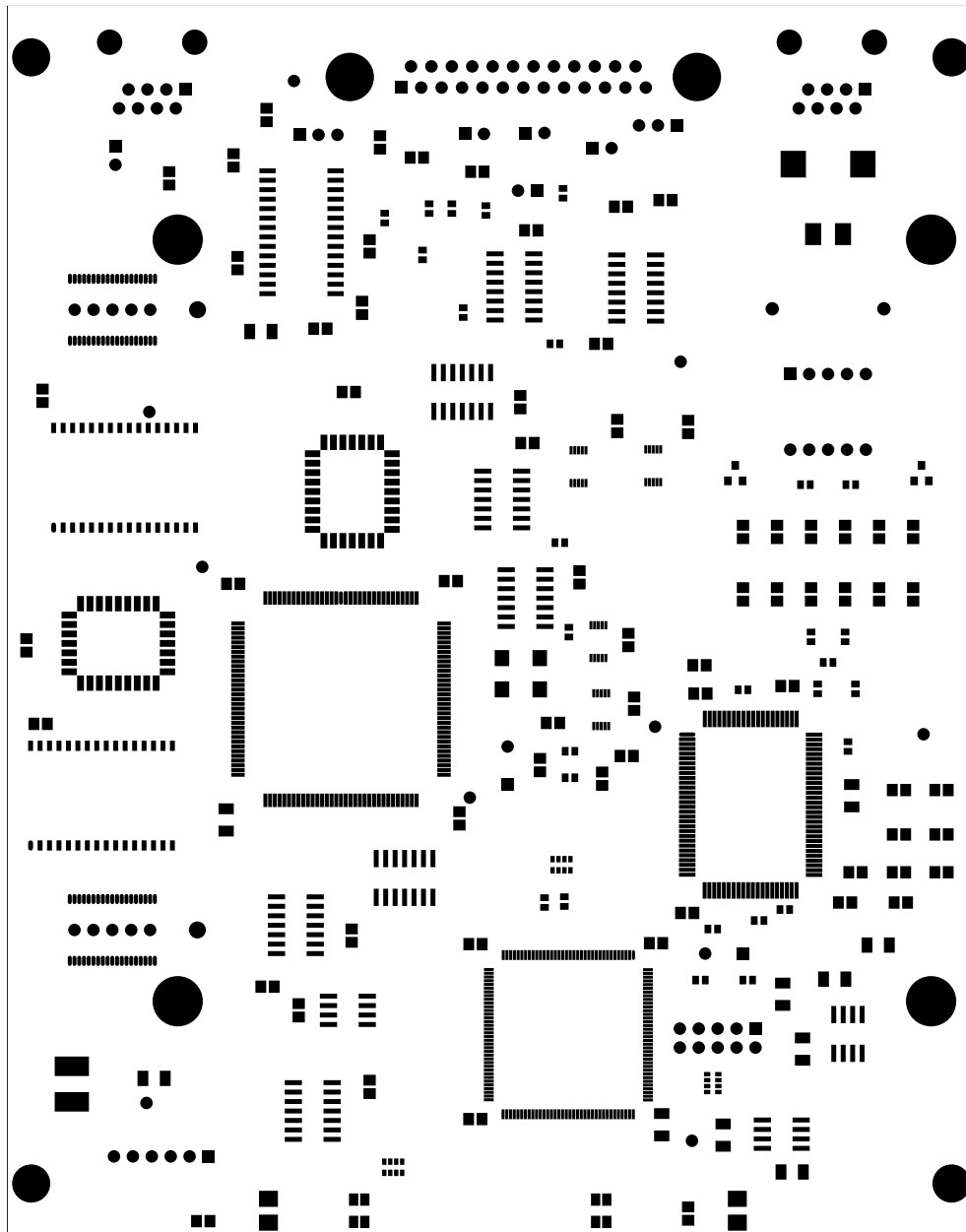2. component
3. solder
4. GNDplane
5. middle1
6. componentmask
7. soldermask
8. plated-drill
9. unplated-drill
10. topsilk
11. bottomsilk
12. bottompaste
13. toppaste
14. topassembly
15. bottomassembly
16. fab

L1

CCCP

OSDCU, front, scale = 1:1.000
OSDCU.pcb

GND

GND

AGND

GND

GND

L4

OSDCU, back (mirrored), scale = 1:1.000
OSDCU.pcb

L2

OSDCU, group2, scale = 1:1.000
OSDCU.pcb

L3

OSDCU, group3, scale = 1:1.000
OSDCU.pcb

OSDCU, frontmask, scale = 1:1.000
OSDCU.pcb

OSDCU, backmask (mirrored), scale = 1:1.000
OSDCU.pcb

OSDCU, plated-drill, scale = 1:1.000
OSDCU.pcb

OSDCU, unplated-drill, scale = 1:1.000
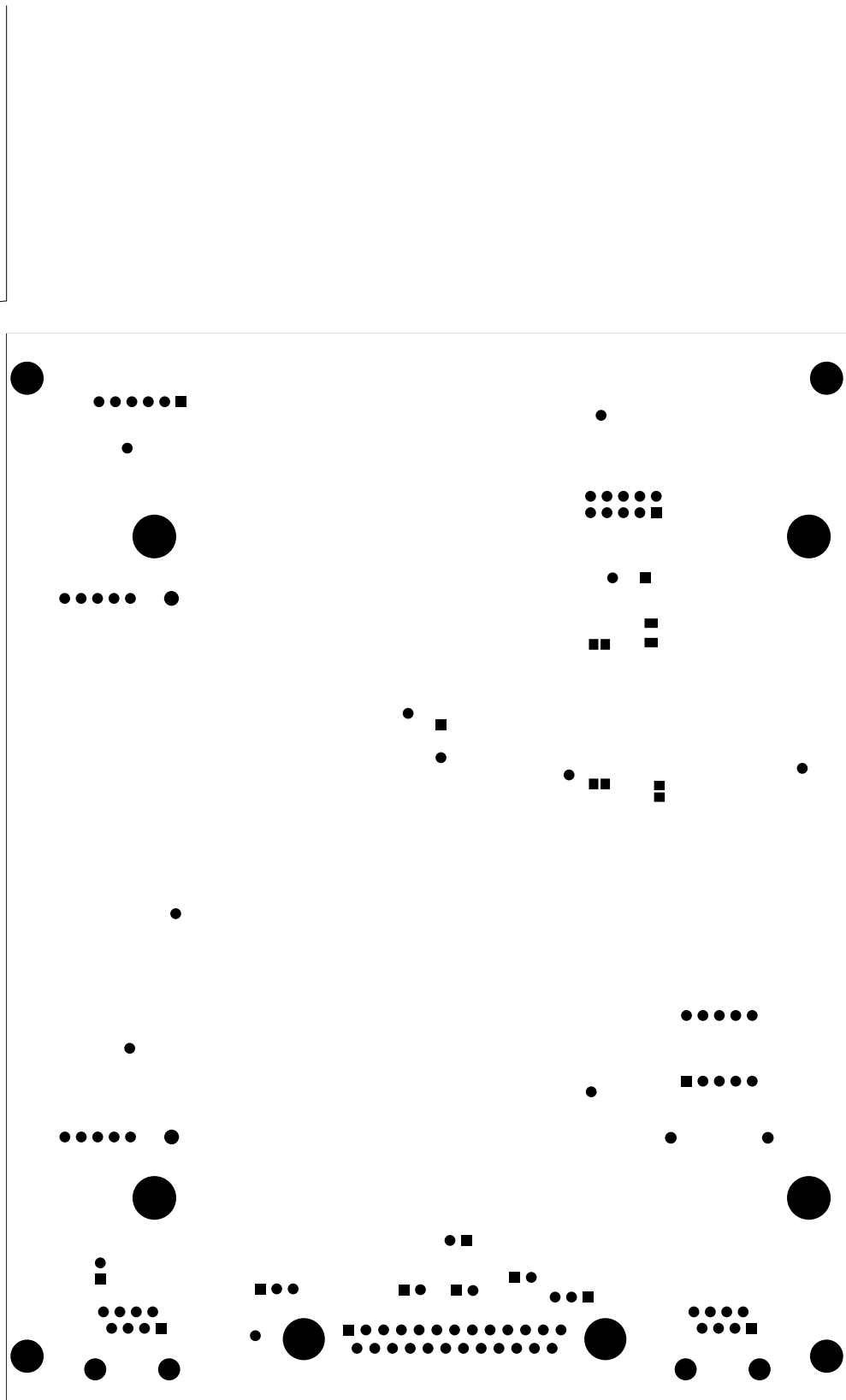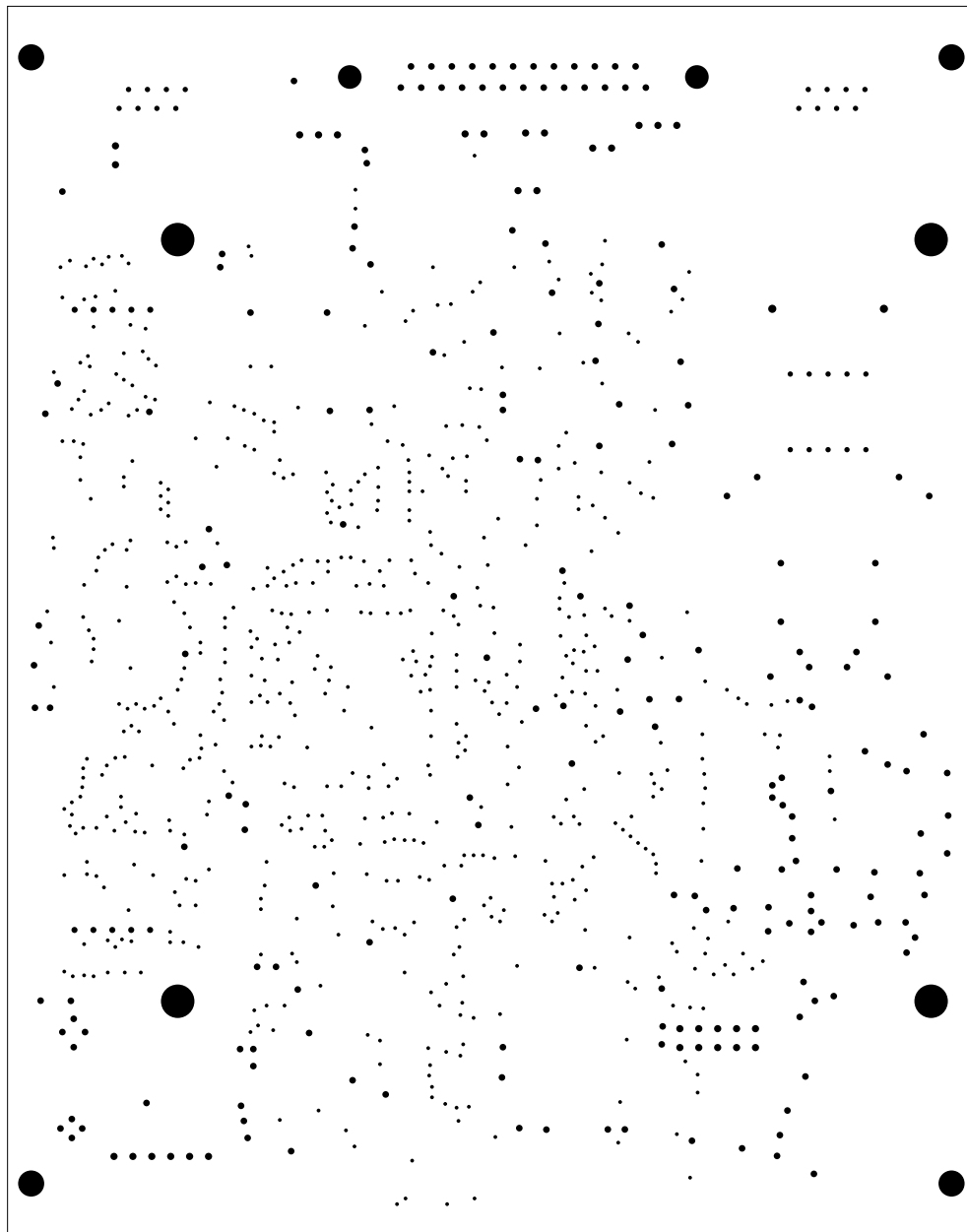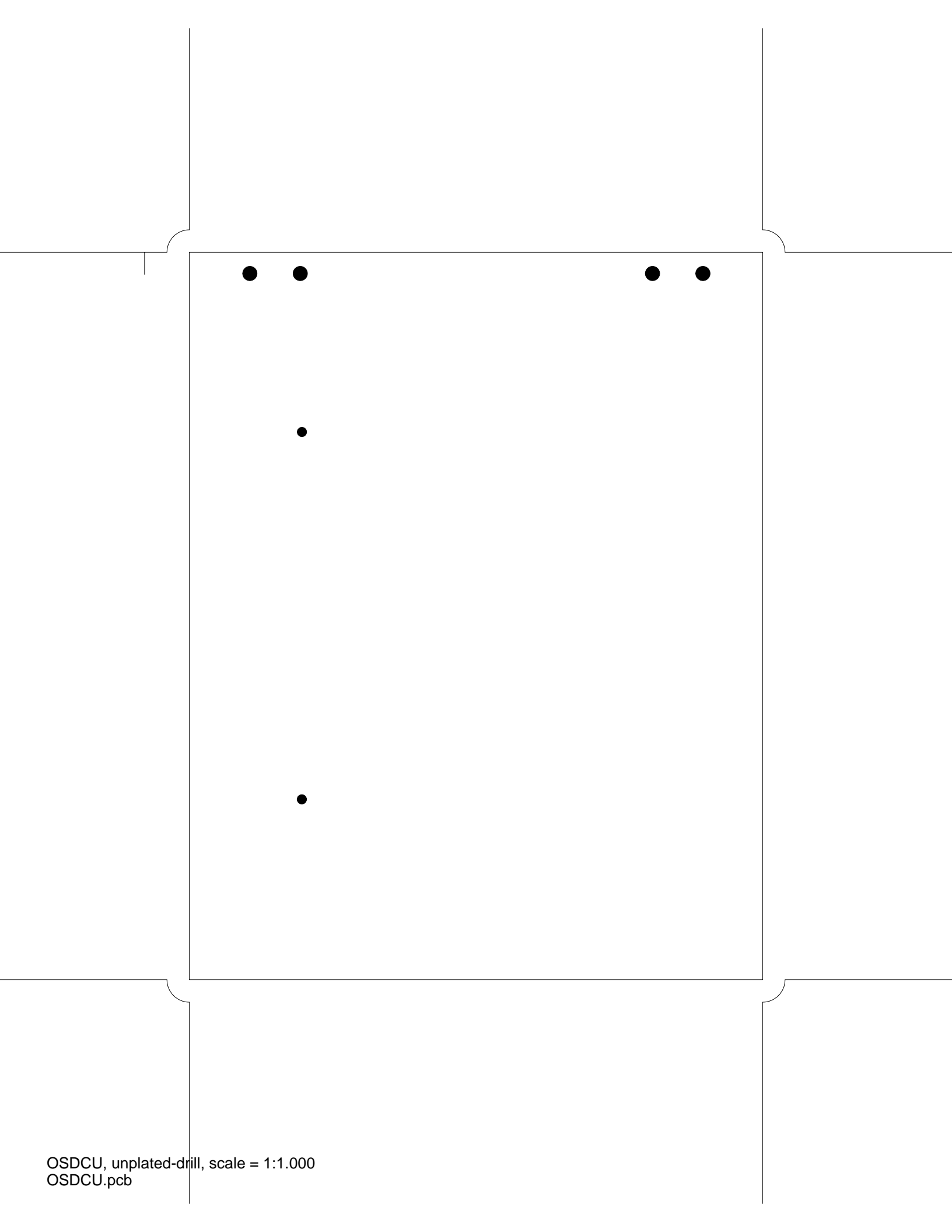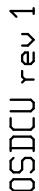OSDCU.pcb

OSDCU, frontsilk, scale = 1:1.000
OSDCU.pcb

SDSL debug instrument
& prototype DSU

Open Source HW design
by Falcon & Ineiev

C16   C15

FPGA_CS_L

BP_CS_L C17   C18

FLASH_CS_L

RAM_CS_L

OSDCU, backsilk (mirrored), scale = 1:1.000
OSDCU.pcb

OSDCU, backpaste (mirrored), scale = 1:1.000
OSDCU.pcb

OSDCU, frontpaste, scale = 1:1.000
OSDCU.pcb

OSDCU, frontassembly, scale = 1:1.000
OSDCU.pcb

SDSL debug instrument
& prototype DSU

Open Source HW design
by Falcon & Ineiev

GND
GND
GND
GND
GND
AGND

C16
C15
C17
C18

FPGA_CS_L
BP_CS_L
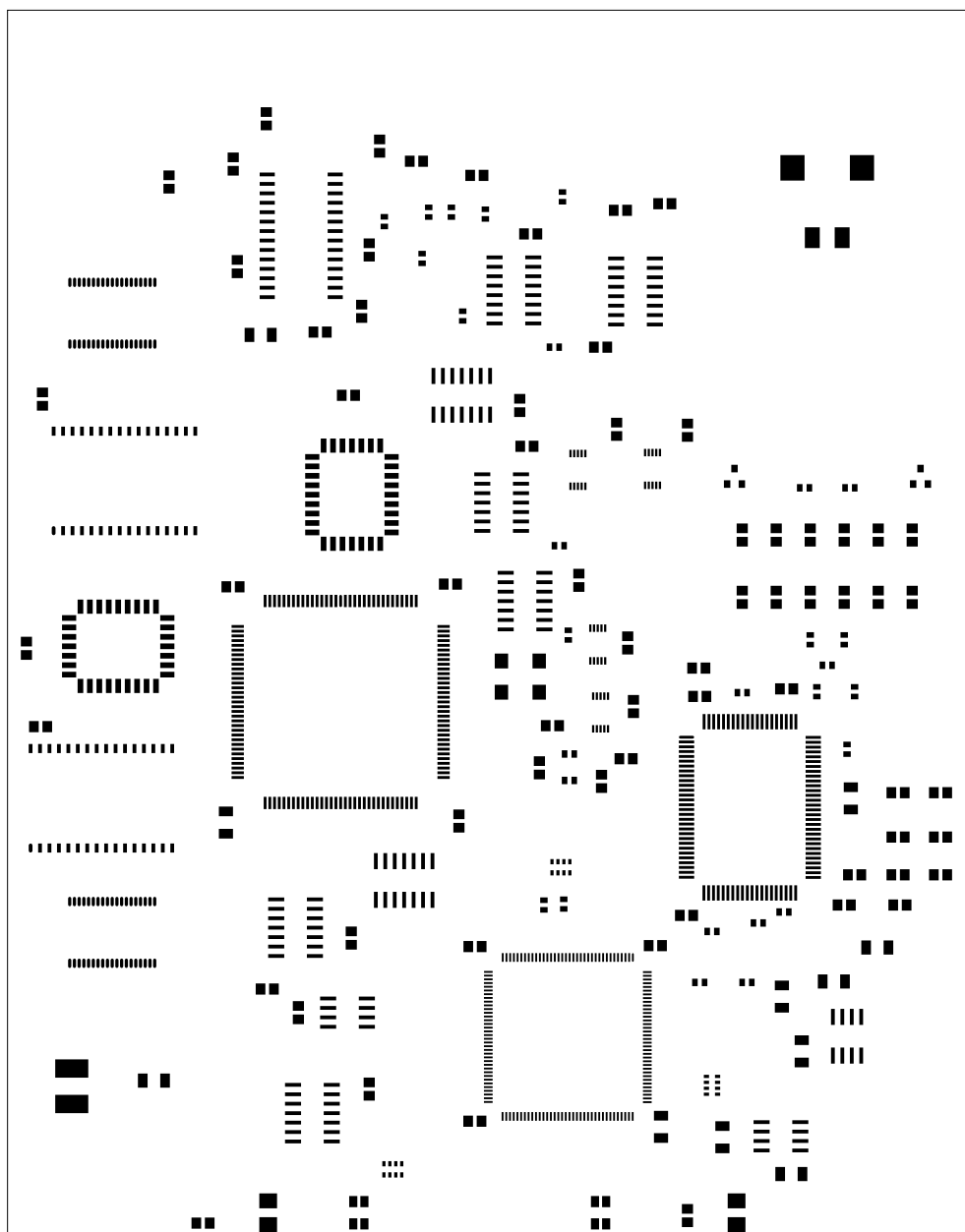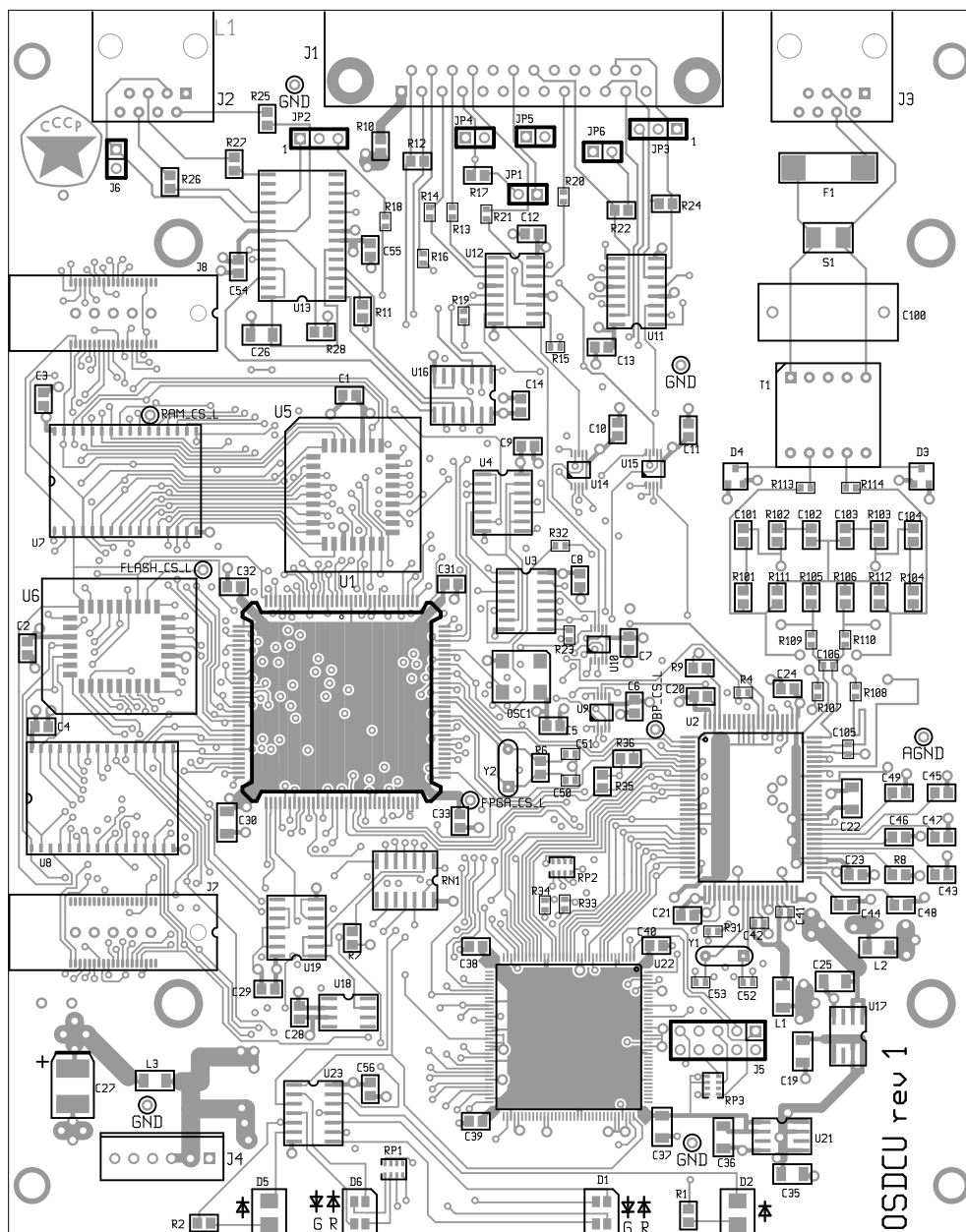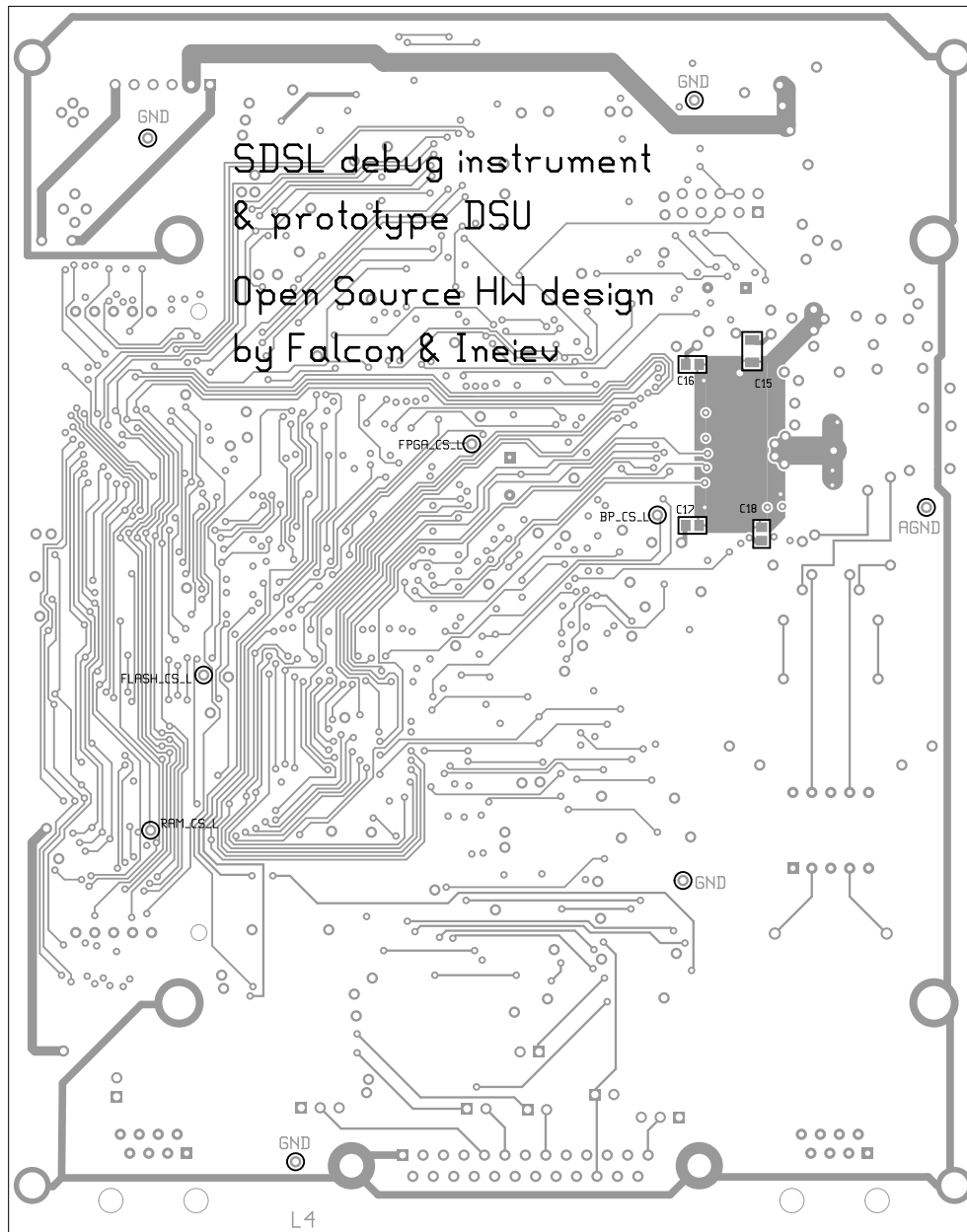FLASH_CS_L
RAM_CS_L

L4

OSDCU, backassembly (mirrored), scale = 1:1.000
OSDCU.pcb

There are 11 different drill sizes used in this layout, 908 holes total

Symbol	Diam. (Inch)	Count	Plated?
Y	0.020	629	YES
+	0.028	26	YES
×	0.032	10	YES
○	0.035	193	YES
□	0.038	32	YES
ⱱ	0.043	2	YES
⊕	0.084	2	NO
⊠	0.125	2	YES
◎	0.128	4	NO
▣	0.138	4	YES
⬤	0.177	4	YES

Title: OSDCU – Fabrication Drawing

Author: Harhan Engineering Co.

Date: Tue Jan 15 06:31:12 2013 UTC

Maximum Dimensions: 5118 mils wide, 6496 mils high

Board outline is the centerline of this 10 mil rectangle – 0,0 to 5118,6496 mils

OSDCU, fab, scale = 1:1.000
OSDCU.pcb